ASSOCIATIO ELECTRONIC	Material Compo © Copyright 2005. IF international and Pan	© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplie	r Information														
Company name*			Company unique ID			ι	Unique ID Authority					Response Date*			
nsemi												2025-05-11			
Contact N	lame		Title - Contact				Phone - Contact*					Email - Contact*			
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date Version Ma		Manufacturing Site		N N	Veight*	UOM	Unit Type		
		AR0144CSSC00SUK 1MP 1/4 CIS A0-CPBR1		1MP 1/4 CIS SO	0		2025-05-11		TWU		νŪ		41.6043	mg	Each
lanufa	cturing Proccess Informat	ion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		Rating	Peak Process Body Temperatu		ure Max Time at Peak Tempera		Temperat	are Nun	nber of Reflow Cy	cles		
SnAgCu		CU Alloy 4			245 C		30		secon	is 3					
omments	3														
or more	information regarding material	composition]	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl halate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.2684	mg	Supplier	Silicon (Si)	7440-21-3		8.2684	mg
Glass Attach Epoxy	0.9839	mg		Miscellaneous	trade secret		0.1279	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.856	mg
Glass Lid /Cap	29.9939	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.9994	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		1.4997	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.4997	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.9994	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		1.4997	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		19.496	mg
Metal Shielding	0.0493	mg	Supplier	Copper (Cu)	7440-50-8		0.0002	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0491	mg
RDL	0.0541	mg	В	Nickel (Ni)	7440-02-0		0.0335	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0202	mg
Solder Ball	2.2207	mg	Supplier	Silver (Ag)	7440-22-4		0.0666	mg
			Supplier	Tin (Sn)	7440-31-5		2.143	mg
			Supplier	Copper (Cu)	7440-50-8		0.0111	mg
Substrate and Solder Mask	0.034	mg	Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0034	mg
			Supplier	9-Phenylacridine	602-56-2		0.0017	mg
			Supplier	2-Propenoic acid	1245638-61-2		0.0034	mg
			Supplier	3-Methoxy-1-butanol	2517-43-3		0.0085	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0085	mg
			Supplier	1-Methoxy-2-propyl acetate (MPA)	108-65-6		0.0085	mg